

Dear Colleagues,

The organising committee of SIITME 2014 kindly invites you to submit an abstract/paper to the **2014 IEEE 20<sup>th</sup> International Symposium for Design and Technology in Electronic Packaging (SIITME)**. The scientific event will take place in Bucharest, on **October 23<sup>rd</sup>–26<sup>th</sup>, 2014**. **Web page:** <http://www.siihme.ro>

## SUBMISSION OF ABSTRACTS AND PAPERS

Interested authors are invited to submit a two-page abstract according to the **template**, as MS-Word document, Version 97 or later, and as PDF document, **attached to an e-mail to [siihme@siihme.ro](mailto:siihme@siihme.ro)**.

**Papers meeting the quality criteria will be included in the IEEE Xplore Digital Library.**

**Abstracts and papers** will be reviewed by the international Scientific Committee.

1. Each abstract will be reviewed on:
  - suitability for one of the topics of the conference
  - scientific content and level, and the relevance of presented results;
  - correspondence with the abstract template, English usage and grammar.Authors of accepted abstracts will be invited to submit a full-length conference paper according to the conference paper template.
2. Papers meeting the following criteria will be published in the Conference Proceedings and will be available through IEEE Xplore:
  - the comments of the reviewers have been taken into consideration;
  - originality of the paper<sup>1</sup> is given;
  - it corresponds with the paper template, English usage and grammar are correct,
  - signed IEEE copyright form has been submitted.

<sup>1</sup> The originality of papers will be checked by the iThenticate plagiarism detection and prevention software.

## TOPICS

- A. Emerging Technologies & Trends in Advanced Packaging, Printed Electronics
- B. Power Electronics and Microsystems Packaging
- C. Assembly and Manufacturing Technology
- D. Design of Electronic Circuits and Systems
- E. Electronics Simulation & Modelling
- F. Electronics Applications and Automotive Electronics
- G. Optoelectronics & Advanced Communication Packaging
- H. Applied Reliability
- I. Challenge in Global Education

## IMPORTANT DATES

Submission of abstracts: **September 7<sup>th</sup>, 2014**

Notification of abstract acceptance: **September 21<sup>st</sup>, 2014**

Submission of camera-ready papers and copyright forms: **October 5<sup>th</sup>, 2014**

Registration deadline: **October 15<sup>th</sup>, 2014**



## CHAIRS

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## CONFERENCE REGISTRATION



The conference fee includes the opening ceremony and welcome reception, full access to all technical (oral and poster) sessions, exhibition area, all meals (breakfasts, coffee breaks, lunches and dinners), three nights accommodation, printed abstracts proceedings, conference proceedings on memory stick, conference kit (conference bag, badge, booklet, pen, and other related objects), and participation to the cultural programme.



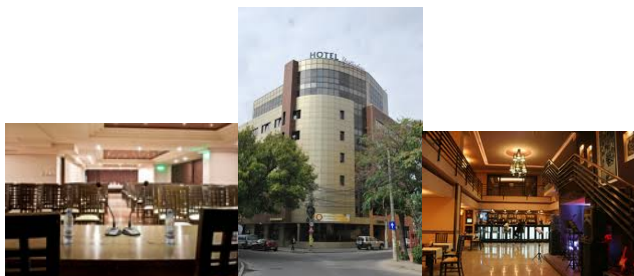
## LOCATION

The conference will take place at:



### Hotel Yesterday

Economu Cezărescu 8  
Bucharest, Romania  
<http://www.yesterday.ro/>



## CONTACT INFORMATION:

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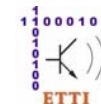
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Faculty of Electronics, Telecommunications and  
Information Technology  
Center for Technological Electronics and  
Interconnection Techniques

# Call for Papers

## SIITME 2014

International Symposium for  
Design and Technology  
in  
Electronic Packaging

